



Features

- Lead free as standard (RoHS compliant*)
- Protects 1 line or 1 I/O port
- Bidirectional configuration
- ESD protection >40 kV
- Low capacitance ~3 pF typical
- Replaces 0805 MLV devices

Applications

- Cell phones
- PDAs and notebooks
- Digital cameras
- MP3 players and GPS
- USB interface

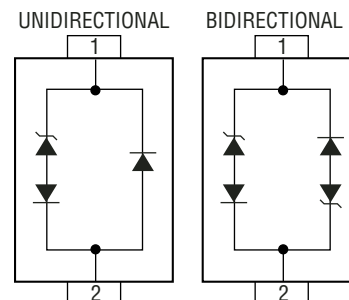
CDSOD323-TxxC – TVS Diode Array Series

General Information

The markets of portable communications, computing and video equipment are challenging the semiconductor industry to develop increasingly smaller electronic components.

Bourns offers Transient Voltage Suppressor Array diodes for surge and ESD protection applications, in SOD323 package size format. The Transient Voltage Suppressor Array series offers a choice of voltage types ranging from 3 V to 24 V in a unidirectional or bidirectional configuration. Bourns® Chip Diodes conform to JEDEC standards, are easy to handle on standard pick and place equipment and their flat configuration minimizes roll away.

The Bourns® device will meet IEC 61000-4-2 (ESD), IEC 61000-4-4 (EFT) and IEC 61000-4-5 (Surge) requirements.



Electrical & Thermal Characteristics (@ $T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8/20\text{ }\mu\text{s}$)	P_{PP}	350	W
Operating Temperature	T_J	-55 $^{\circ}\text{C}$ to 150 $^{\circ}\text{C}$	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55 $^{\circ}\text{C}$ to 150 $^{\circ}\text{C}$	$^{\circ}\text{C}$

Parameter	Symbol	CDSOD323-								Unit
		Uni-T03	Bi-T03C	Uni-T05	Bi-T05C	Uni-T08	Bi-T08C	Uni-T12	Bi-T12C	
Min. Breakdown Voltage @ 1 mA	V_{BR}	4.0	4.0	6.0	6.0	8.5	8.5	13.3	13.3	V
Working Peak Voltage	V_{WM}	3.3	3.3	5.0	5.0	8.0	8.0	12.0	12.0	V
Maximum Clamping Voltage @ $I_p = 1\text{ A}$	V_F	7.0	7.0	9.8	9.8	13.4	13.4	19.0	19.0	V
Maximum Clamping Voltage @ 8/20 μs @ I_{pp}	V_C	19.0 V @ 20 A	19.0 V @ 20 A	18.3 V @ 17 A	18.3 V @ 17 A	18.5 V @ 17 A	18.5 V @ 17 A	28.3 V @ 11 A	28.3 V @ 11 A	V
Maximum Leakage Current @ V_{WM}	I_D	5	5	5	5	2	2	1	1	μA
Typical Capacitance @ 0 V, 1 MHz	C_J	3								pF

Notes:

1. Part numbers with suffix "C" indicate bidirectional device, i.e. CDSOD323-T05C.
2. For bidirectional devices only, the electrical specifications apply in both directions.

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Electrical & Thermal Characteristics (@ $T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

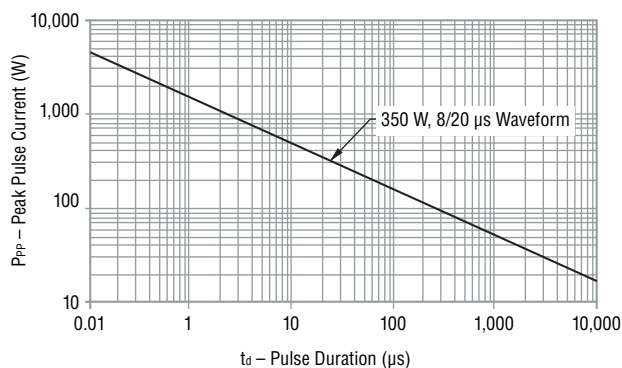
Parameter	Symbol	CDSOD323-						Unit
		Uni-T15	Bi-T15C	Uni-T18	Bi-T18C	Uni-T24	Bi-T24C	
Min. Breakdown Voltage @ 1 mA	V_{BR}	16.7	16.7	20.0	20.0	26.7	26.7	V
Working Peak Voltage	V_{WM}	15.0	15.0	18.0	18.0	24.0	24.0	V
Maximum Clamping Voltage @ $I_P = 1\text{ A}$	V_F	24.0	24.0	29.0	29.0	43.0	43.0	V
Maximum Clamping Voltage @ 8/20 μs @ I_{PP}	V_C	31.8 V @ 10 A	31.8 V @ 10 A	45.0 V @ 8 A	45.0 V @ 8 A	56.0 V @ 6 A	56.0 V @ 6 A	V
Maximum Leakage Current @ V_{WM}	I_D	1						μA
Typical Capacitance @ 0 V, 1 MHz	C_J	3						pF

Notes:

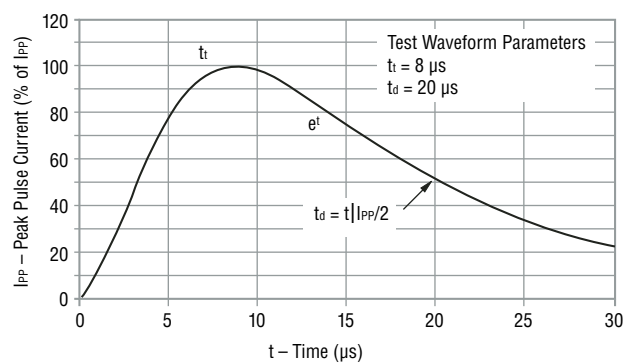
- Part numbers with suffix "C" indicate bidirectional device, i.e. CDSOD323-T05C.
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Performance Graphs

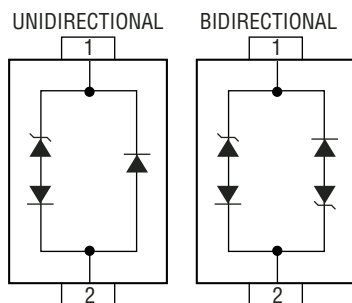
Peak Pulse Power vs Pulse Time



Pulse Wave Form



Block Diagram



How To Order

Common Code _____
 Chip Diode _____
 Package _____
 • SOD323 = SOD-323 Package
 Model _____
 T = Transient Voltage Suppressor
 Working Peak Reverse Voltage _____
 05 = 5 V_{RWM} (Volts)
 Suffix _____
 C = Bidirectional Diode

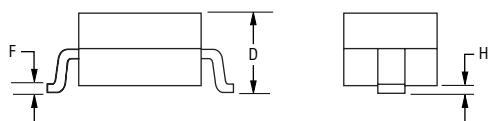
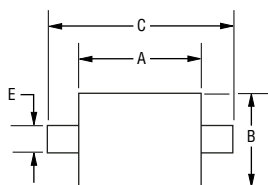
CD SOD323 - T 05 C

CDSOD323-TxxC – TVS Diode Array Series

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Product Dimensions

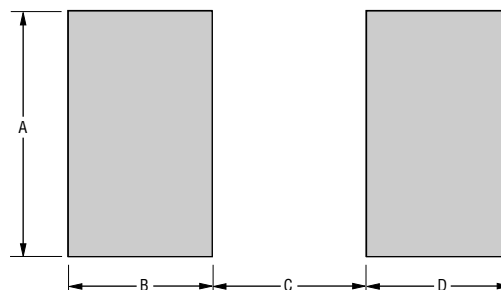
This is a molded JEDEC SOD-323 package with lead free 100 % Sn plating on the terminations. It weighs approximately 30 mg and has a flammability rating of UL 94V-0.



Dimensions	
A	$\frac{0.60 - 1.90}{0.063 - 0.075}$
B	$\frac{1.15 - 1.45}{0.045 - 0.057}$
C	$\frac{2.39 - 2.70}{0.094 - 0.106}$
D	$\frac{0.92 - 1.10}{0.036 - 0.043}$
E	$\frac{0.25 - 0.40}{0.010 - 0.016}$
F	$\frac{0.10 - 0.20}{0.004 - 0.008}$
H	$\frac{0.10}{0.004} \text{ MAX.}$

DIMENSIONS = $\frac{\text{MILLIMETERS}}{(\text{INCHES})}$

Recommended Footprint



Dimensions (Nominal)	
A	$\frac{0.80}{0.031}$
B	$\frac{0.80}{0.031}$
C	$\frac{1.40}{0.055}$
D	$\frac{0.80}{0.031}$

DIMENSIONS = $\frac{\text{MILLIMETERS}}{(\text{INCHES})}$

Typical Part Marking

Each device has device marking outlined below and the unidirectional devices have an additional Polarity Band indicating the cathode.

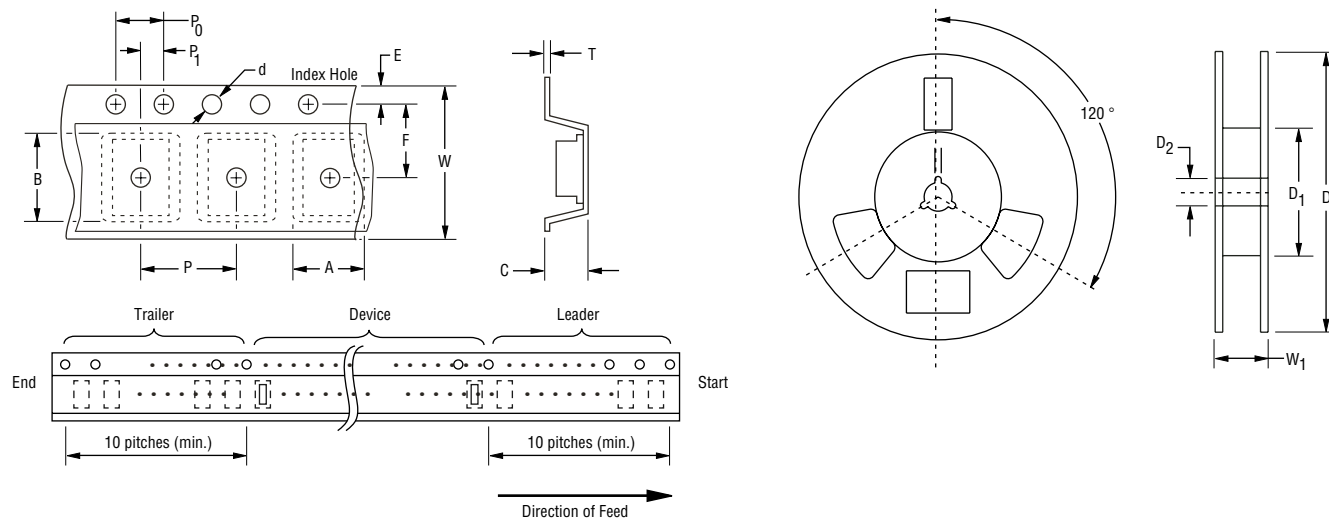
CDSOD323-T03	3
CDSOD323-T03C	3C
CDSOD323-T05	5
CDSOD323-T05C	5C
CDSOD323-T08	8
CDSOD323-T08C	8C
CDSOD323-T12	2
CDSOD323-T12C	2C
CDSOD323-T15	6
CDSOD323-T15C	6C
CDSOD323-T18	1
CDSOD323-T18C	1C
CDSOD323-T24	4
CDSOD323-T24C	4C

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Packaging Information

The surface mount product is packaged in an 8 mm x 4 mm tape and reel format per EIA-481 standard.



Item	Symbol	SOD-323
Carrier Width	A	$\frac{1.55 \pm 0.10}{(0.061 - 0.004)}$
Carrier Length	B	$\frac{2.90 \pm 0.10}{(0.114 - 0.004)}$
Carrier Depth	C	$\frac{1.35 \pm 0.10}{(0.053 - 0.004)}$
Sprocket Hole	d	$\frac{1.55 \pm 0.05}{(0.061 - 0.002)}$
Reel Outside Diameter	D	$\frac{178}{(7.008)}$
Reel Inner Diameter	D1	$\frac{80.0}{(3.150)} \text{ Min.}$
Feed Hole Diameter	D2	$\frac{13.0 \pm 0.20}{(0.512 - 0.008)}$
Sprocket Hole Position	E	$\frac{1.75 \pm 0.10}{(0.069 - 0.004)}$
Punch Hole Position	F	$\frac{3.50 \pm 0.05}{(0.138 - 0.002)}$
Punch Hole Pitch	P	$\frac{4.00 \pm 0.10}{(0.157 - 0.004)}$
Sprocket Hole Pitch	P0	$\frac{4.00 \pm 0.10}{(0.157 - 0.004)}$
Embossment Center	P1	$\frac{2.00 \pm 0.05}{(0.079 - 0.002)}$
Overall Tape Thickness	T	$\frac{0.20 \pm 0.10}{(0.008 - 0.004)}$
Tape Width	W	$\frac{8.00 \pm 0.20}{(0.315 - 0.008)}$
Reel Width	W1	$\frac{13.5}{(0.531)} \text{ Max.}$
Quantity per Reel	—	3,000



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Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.